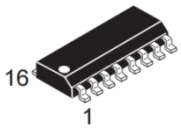
Presettable synchronous BCD decade up/down counter

FEATURES

- Synchronous reversible counting
- Asynchronous parallel load
- Asynchronous reset
- Expandable without external logic
- Output capability: standard
- I_{CC} category: MSI



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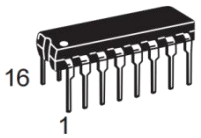

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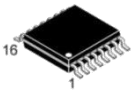


TSSOP-16

PACKAGE/ORDERING INFORMATION

DEVICE	Package Type	MARKING	Packing	Packing Qty
74HC192N	DIP-16	74HC192	TUBE	1000pcs/Box
74HC192M/TR	SOP-16	74HC192	REEL	2500pcs/Reel
74HC192MT/TR	TSSOP-16	HC192	REEL	2500pcs/Reel
74HCT192N	DIP-16	74HCT192	TUBE	1000pcs/Box
74HCT192M/TR	SOP-16	74HCT192	REEL	2500pcs/Reel
74HCT192MT/TR	TSSOP-16	HCT192	REEL	2500pcs/Reel

GENERAL DESCRIPTION

The 74HC/HCT192 are high-speed Si-gate CMOS devices and are pin compatible with low power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard no. 7A.

The 74HC/HCT192 are synchronous BCD up/down counters. Separate up/down clocks, CP_U and CPD respectively, simplify operation. The outputs change state synchronously with the LOW-to-HIGH transition of either clock input. If the CP_U clock is pulsed while CPD is held HIGH, the device will count up. If the CPD clock is pulsed while CPU is held HIGH, the device will count down. Only one clock input can be held HIGH at any time, or erroneous operation will result. The device can be cleared at any time by the asynchronous master reset input (MR); it may also be loaded in parallel by activating the asynchronous parallel load input ($\overline{PL}$).

The “192” contains four master-slave JK flip-flops with the necessary steering logic to provide the asynchronous reset, load, and synchronous count up and count down functions.

Each flip-flop contains JK feedback from slave to master, such that a LOW-to-HIGH transition on the CPD input will decrease the count by one, while a similar transition on the CPU input will advance the count by one.

One clock should be held HIGH while counting with the other, otherwise the circuit will either count by two’s or not at all, depending on the state of the first flip-flop, which cannot toggle as long as either clock input is LOW. Applications requiring reversible operation must make the reversing decision while the activating clock is HIGH to avoid erroneous counts.

The terminal count up ($\overline{TC}_U$) and terminal count down ($\overline{TC}D$) outputs are normally HIGH. When the circuit has reached the maximum count state of 9, the next HIGH-to-LOW transition of CP_U will cause $\overline{TC}_U$ to go LOW. $\overline{TC}_U$ will stay LOW until CP_U goes HIGH again, duplicating the count up clock.

Likewise, the $\overline{TC}_D$ output will go LOW when the circuit is in the zero state and the CPD goes LOW. The terminal count outputs can be used as the clock input signals to the next higher order circuit in a multistage counter, since they duplicate the clock wave forms. Multistage counters will not be fully synchronous, since there is a slight delay time difference added for each stage that is added.

The counter may be preset by the asynchronous parallel load capability of the circuit. Information present on the parallel data inputs (D_0 to D_3) is loaded into the counter and appears on the outputs (Q_0 to Q_3) regardless of the conditions of the clock inputs when the parallel load ($\overline{PL}$) input is LOW. A HIGH level on the master reset (MR) input will disable the parallel load gates, override both clock inputs and set all outputs (Q_0 to Q_3) LOW. If one of the clock inputs is LOW during and after a reset or load operation, the next LOW-to-HIGH transition of that clock will be interpreted as a legitimate signal and will be counted.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25°C; $t_r = t_f$ = 6 ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL		UNIT
			HC	HCT	
t_{PHL}/ t_{PLH}	propagation delay CPD, CPU to Qn	CL = 15 pF; VCC =5V	20	20	ns
f_{max}	maximum clock frequency		40	45	MHz
T_L	Soldering temperature	10s	-	245	°C
C_I	input capacitance		3.5	3.5	pF
C_{PD}	power dissipation capacitance per package	notes 1 and 2	24	28	pF

Notes: 1、CPD is used to determine the dynamic power dissipation (PD in μW):
$P_D = C_{PD} \times V_{CC}^2 \times fi + \Sigma(CL \times V_{CC}^2 \times F_O)$ where:
fi=input frequency in MHz
fo=output frequency in MHz
$\Sigma(CL \times V_{CC}^2 \times F_O)$=sum of outputs
C_L = output load capacitance in pF
V_{CC} = supply voltage in V

2、For HC the condition is V_I = GND to VCC
For HCT the condition is V_I = GND to VCC-1.5V

PIN DESCRIPTION

PIN NO.	SYMBOL	NAME AND FUNCTION
3, 2, 6, 7	Q0 to Q3	flip-flop outputs
4	CP_D	count down clock input(1)
5	CP_U	count up clock input(1)
8	GND	ground (0 V)
11	$\overline{PL}$	asynchronous parallel load input (active LOW)
12	$\overline{TC}_U$	terminal count up (carry) output (active LOW)
13	$\overline{TC}_D$	terminal count down (borrow) output (active LOW)
14	MR	asynchronous master reset input (active HIGH)
15, 1, 10, 9	D_0 to D_3	data inputs
16	V_{CC}	positive supply voltage

Note

1. LOW-to-HIGH, edge triggered

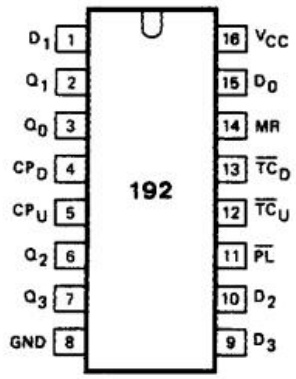


Fig.1 Pin configuration.

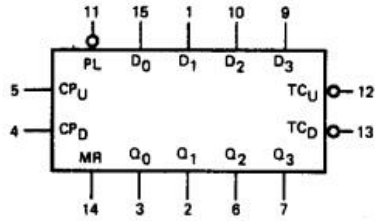


Fig.2 Logic symbol.

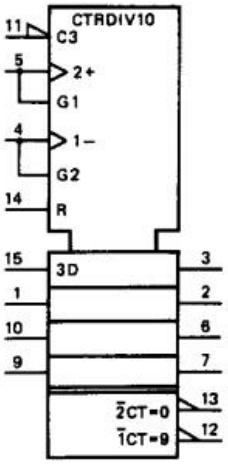


Fig.3 IEC logic symbol.

FUNCTION TABLE

OPERATING MODE	INPUTS								OUTPUTS					
	MR	$\overline{PL}$	CPU	CPD	D0	D1	D2	D3	Q0	Q1	Q2	Q3	$\overline{TC}_U$	$\overline{TC}_D$
reset (clear)	H	X	X	L	X	X	X	X	L	L	L	L	H	L
	H	X	X	H	X	X	X	X	L	L	L	L	H	H
parallel load	L	L	X	L	L	L	L	L	L	L	L	L	H	L
	L	L	X	H	L	L	L	L	L	L	L	L	H	H
	L	L	L	X	H	X	X	H	Qn = Dn				L	H
	L	L	H	X	H	X	X	H	Qn = Dn				H	H
count up	L	H		H	X	X	X	X	count up				H[2]	H
count down	L	H	H		X	X	X	X	count down				H	H[3]

Notes

H = HIGH voltage level

L = LOW voltage level

X = don't care

↑= LOW-to-HIGH clock transition

$\overline{TC}_U$ = CPU at terminal count up (HLLH)

$\overline{TC}_D$ = CPD at terminal count down (LLLL)

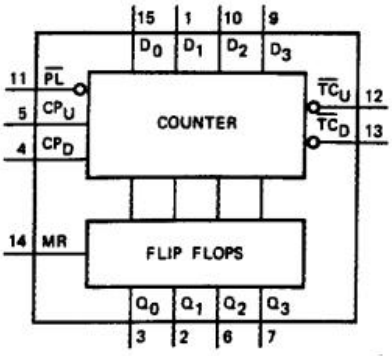
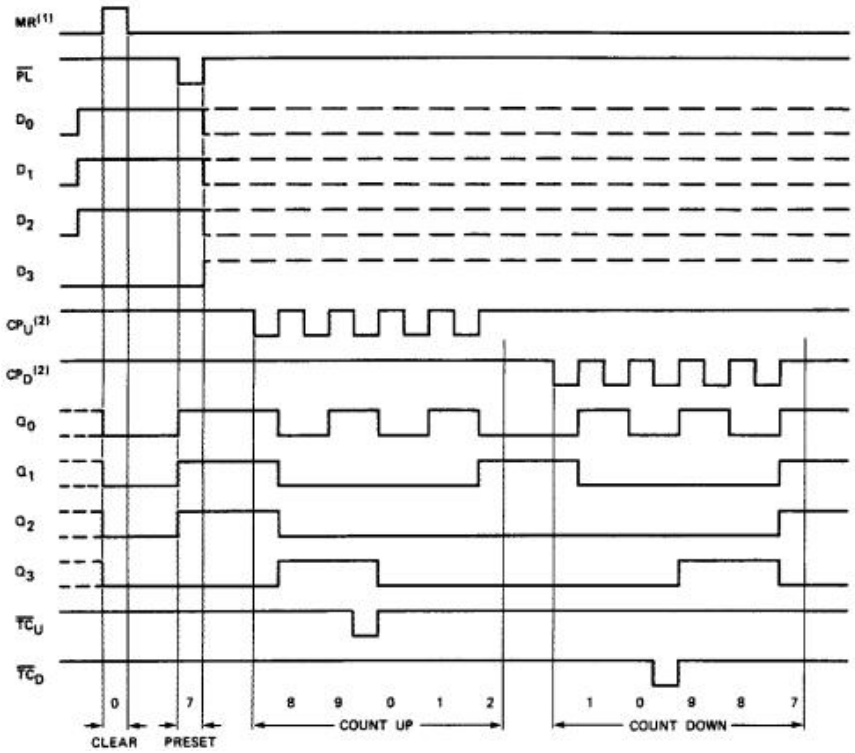


Fig.4 Functional diagram.



Clear overrides load, data and count inputs.

When counting up the count down clock input (CPD) must be HIGH, when counting down the count up clock input (CPU) must be HIGH.

Sequence

Clear (reset outputs to zero); load (preset) to BCD seven; count up to eight, nine, terminal count up, zero, one and two; count down to one, zero, terminal count down, nine, eight, and seven.

Fig.5 Typical clear, load and count sequence.

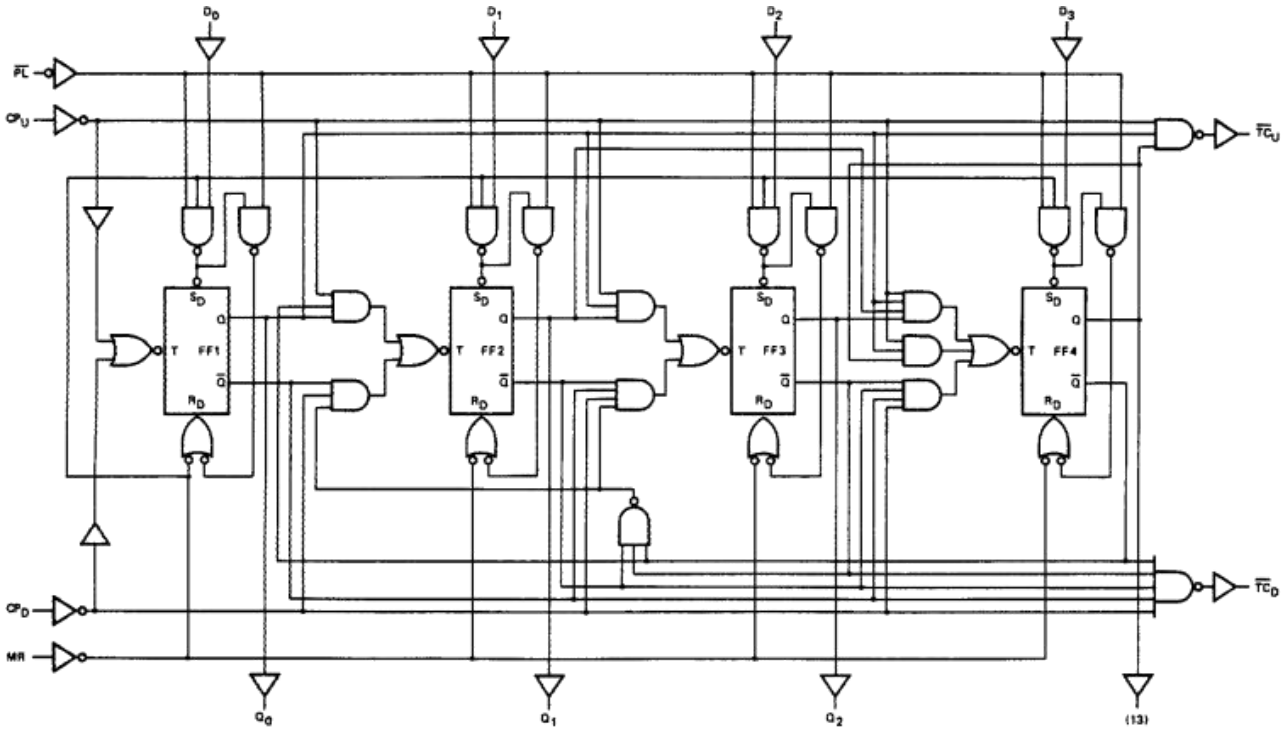


Fig.6 Logic diagram.

DC CHARACTERISTICS FOR 74HC

Output capability: standard

Icc category: MSI

AC CHARACTERISTICS FOR 74HC

GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF

SYMBOL	PARAMETER	Tamb (°C)							UNIT	TEST CONDITIONS	
		74HC								VCC (V)	WAVEFORMS
		25			-40 to +85		-40 to +125				
		min.	typ.	max.	min.	max.	min.	max.			
t_{PHL}/ t_{PLH}	propagation delay CP_U, CP_D to Qn		66 24 19	215 43 37		270 54 46		325 65 55	ns	2.0 4.5 6.0	Fig.7
t_{PHL}/ t_{PLH}	propagation delay CP_U to TC_U		33 12 10	125 25 21		155 31 26		190 38 32	ns	2.0 4.5 6.0	Fig.8
t_{PHL}/ t_{PLH}	propagation delay CP_D to TC_D		39 14 11	125 25 21		155 31 26		190 38 32	ns	2.0 4.5 6.0	Fig.8
t_{PHL}/ t_{PLH}	propagation delay $\overline{PL}$ to Qn		69 25 20	215 43 37		270 54 46		325 65 55	ns	2.0 4.5 6.0	Fig.9
t_{PHL}	propagation delay MR to Qn		63 23 18	200 40 34		250 50 43		300 60 51	ns	2.0 4.5 6.0	Fig.10
t_{PHL}	propagation delay Dn to Qn		91 33 26	275 55 47		345 69 59		415 83 71	ns	2.0 4.5 6.0	Fig.9
t_{PHL}	propagation delay Dn to Qn		80 29 23	240 48 41		300 60 51		360 72 61	ns	2.0 4.5 6.0	Fig.9
t_{PHL}/ t_{PLH}	propagation delay $\overline{PL}$ to TCU, $\overline{PL}$ to $\overline{TC_D}$		102 37 30	315 63 54		395 79 67		475 95 81	ns	2.0 4.5 6.0	Fig.12
t_{PHL}/ t_{PLH}	propagation delay MR to $\overline{TC_U}$, MR to $\overline{TC_D}$		96 35 28	285 57 48		355 71 60		430 86 73	ns	2.0 4.5 6.0	Fig.12
t_{PHL}/ t_{PLH}	propagation delay Dn to $\overline{TC_U}$, Dn to $\overline{TC_D}$		83 30 24	290 58 49		365 73 62		435 87 74	ns	2.0 4.5 6.0	Fig.12
t_{THL}/ t_{TLH}	output transition time		19 7 6	75 15 13		95 19 16		110 22 19	ns	2.0 4.5 6.0	Fig.10

SYMBOL	PARAMETER	Tamb (°C)							UNIT	TEST CONDITIONS	
		74HC								VCC (V)	WAVEFORMS
		+25			-40 to +85		-40 to +125				
		min.	typ.	max.	min.	max.	min.	max.			
tW	up clock pulse width HIGH or LOW	120 24 20	39 14 11		150 30 26		180 36 31		ns	2.0 4.5 6.0	Fig.7
tW	down clock pulse width HIGH or LOW	140 28 24	50 18 14		175 35 30		210 42 36		ns	2.0 4.5 6.0	Fig.7
tW	master reset pulse width HIGH	80 16 14	22 8 6		100 20 17		120 24 20		ns	2.0 4.5 6.0	Fig.10
tW	parallel load pulse width LOW	80 16 14	22 8 6		100 20 17		120 24 20		ns	2.0 4.5 6.0	Fig.9
trem	removal time PL to CPU, CPD	50 10 9	3 1 1		65 13 11		75 15 13		ns	2.0 4.5 6.0	Fig.9
trem	removal time MR to CPU, CPD	50 10 9	0 0 0		65 13 11		75 15 13		ns	2.0 4.5 6.0	Fig.10
tsu	set-up time Dn to PL	80 16 14	22 8 6		100 20 17		120 24 20		ns	2.0 4.5 6.0	Fig.11 note: CP_U = CP_D = HIGH
th	hold time Dn to PL	0 0 0	14 5 4		0 0 0		0 0 0		ns	2.0 4.5 6.0	Fig.11
th	hold time CPU to CPD, CPD to CPU	80 16 14	19 7 6		100 20 17		120 24 20		ns	2.0 4.5 6.0	Fig.13
fmax	maximum up, down clock pulse frequency	4.0 20 24	12 36 43		3.2 16 19		2.6 13 15		MHz	2.0 4.5 6.0	Fig.7

DC CHARACTERISTICS FOR 74HCT

Output capability: standard I_{CC} category: MSI

Note to HCT types

The value of additional quiescent supply current (ΔICC) for a unit load of 1 is given in the family specifications.

To determine ΔICC per input, multiply this value by the unit load coefficient shown in the table below.

INPUT	UNIT LOAD COEFFICIENT
Dn	0.35
CP_U, CP_D	1.40
PL	0.65
MR	1.05

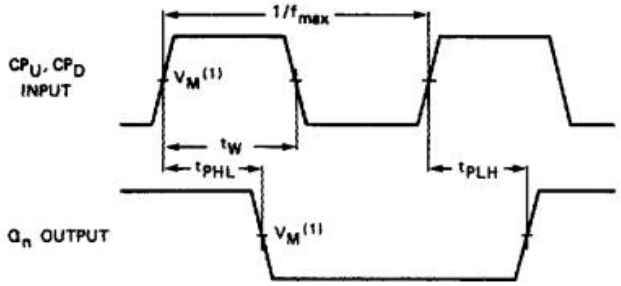
AC CHARACTERISTICS FOR 74HCT

GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF

SYMBOL	PARAMETER	Tamb (°C)							UNIT	TEST CONDITIONS	
		74HCT								VCC (V)	WAVEFORMS
		+25			-40 to +85		-40 to +125				
		min.	typ.	max.	min.	max.	min.	max.			
t_{PHL}/ t_{PLH}	propagation delay CP_U, CP_D to Qn		23	43		54		65	ns	4.5	Fig.7
t_{PHL}/ t_{PLH}	propagation delay CPU to $\overline{TC}_U$		16	30		38		45	ns	4.5	Fig.8
t_{PHL}/ t_{PLH}	propagation delay CPD to $\overline{TC}_D$		17	30		38		45	ns	4.5	Fig.8
t_{PHL}/ t_{PLH}	propagation delay $\overline{PL}$ to Qn		28	46		58		69	ns	4.5	Fig.9
t_{PHL}	propagation delay MR to Qn		24	40		50		60	ns	4.5	Fig.10
t_{PHL}/ t_{PLH}	propagation delay Dn to Qn		36	62		78		93	ns	4.5	Fig.9
t_{PHL}/ t_{PLH}	propagation delay $\overline{PL}$ to $\overline{TC}_U$, PL to $\overline{TC}_D$		36	64		80		96	ns	4.5	Fig.12
t_{PHL}/ t_{PLH}	propagation delay MR to $\overline{TC}_U$, MR to $\overline{TC}_D$		36	64		80		96	ns	4.5	Fig.12
t_{PHL}/ t_{PLH}	propagation delay Dn to $\overline{TC}_U$, Dn to $\overline{TC}_D$		33	58		73		87	ns	4.5	Fig.12
t_{THL}/ t_{TLH}	output transition time		7	15		19		22	ns	4.5	Fig.10
t_W	up, down clock pulse width HIGH or LOW	25	14		31		38		ns	4.5	Fig.7

t_W	master reset pulse width HIGH	16	6		20		24		ns	4.5	Fig.10
t_W	parallel load pulse width LOW	20	10		25		30		ns	4.5	Fig.9
trem	removal time $\overline{PL}$ to CP_U, CP_D	10	1		13		15		ns	4.5	Fig.9
trem	removal time MR to CP_U, CP_D	10	2		13		15		ns	4.5	Fig.10
tsu	set-up time Dn to $\overline{PL}$	16	8		20		24		ns	4.5	Fig.11 note: CP_U=CP_D = HIGH
th	hold time Dn to $\overline{PL}$	0	-6		0		0		ns	4.5	Fig.11
th	hold time CP_U to CP_D, CP_D to CP_U	20	9		25		30		ns	4.5	Fig.13
fmax	maximum up, down clock pulse frequency	20	41		16		13		MHz	4.5	Fig.7

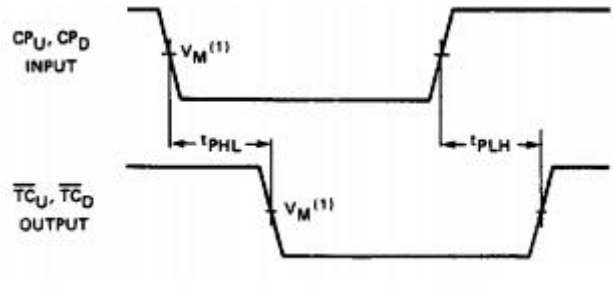
AC WAVEFORMS



(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

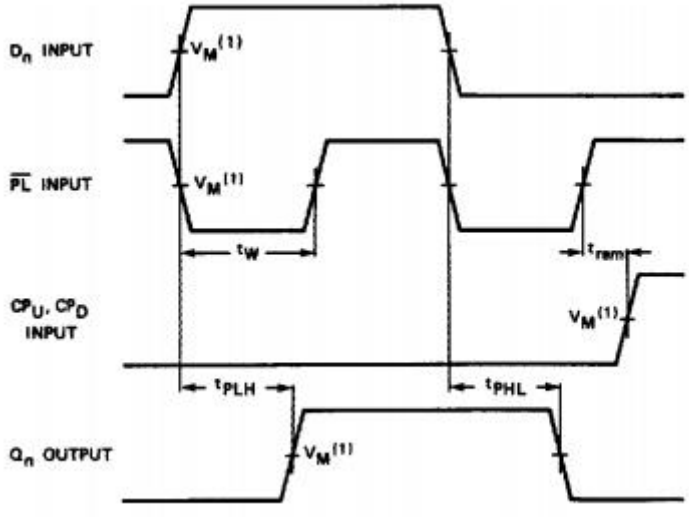
Fig.7 Wave forms showing the clock (CP_U, CP_D) to output (Qn) propagation delays, the clock pulse width and the maximum clock pulse frequency.



(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

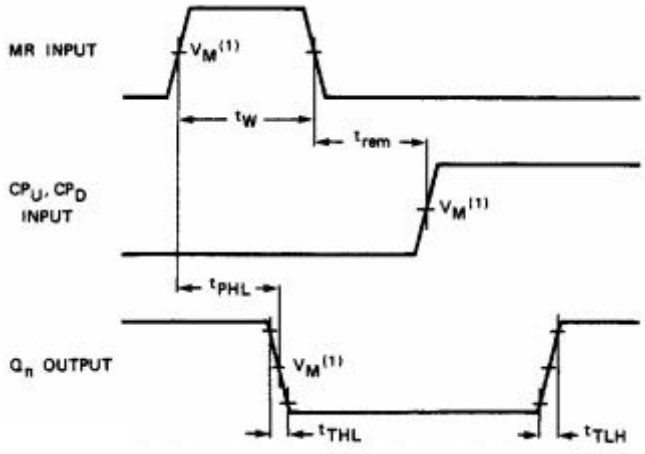
Fig.8 Wave forms showing the clock (CP_U, CP_D) to terminal count output ($\overline{TC}_U$, $\overline{TC}_D$) propagation delays.



(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

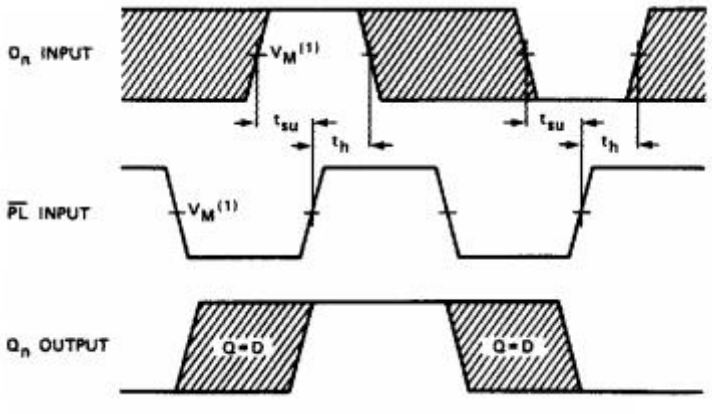
Fig.9 Wave forms showing the parallel load input ($\overline{PL}$) and data (Dn) to Qn output propagation delays and $\overline{PL}$ removal time to clock input (CP_U, CP_D).



(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

Fig.10 Wave forms showing the master reset input (MR) pulse width, MR to Qn propagation delays, MR to CP_U, CP_D removal time and output transition times.

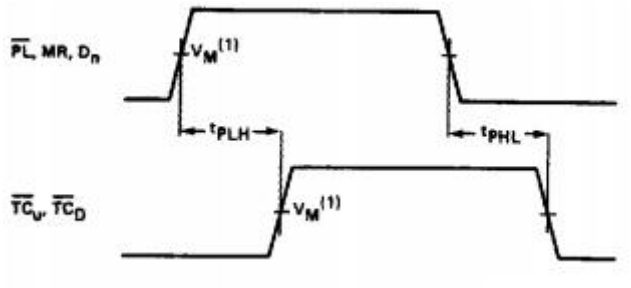


The shaded areas indicate when the input is permitted to change for predictable output performance.

(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

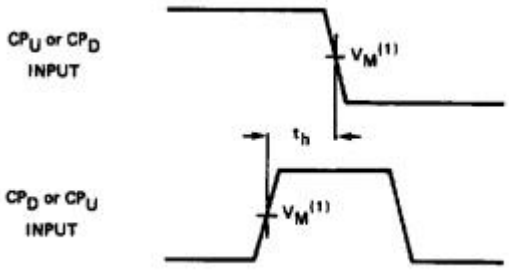
Fig.11 Waveforms showing the data input (Dn) to parallel load input ($\overline{PL}$) set-up and hold times.



(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

Fig.12 Waveforms showing the data input (Dn), parallel load input ($\overline{PL}$) and the master reset input (MR) to the terminal count outputs ($\overline{TC}_U$, $\overline{TC}_D$) propagation delays.



(1) HC : V_M = 50%; V_I = GND to V_{CC}.

HCT: V_M = 1.3 V; V_I = GND to 3 V.

Fig.13 Waveforms showing the CP_U to CP_D or CPD to CPU hold times.

APPLICATION INFORMATION

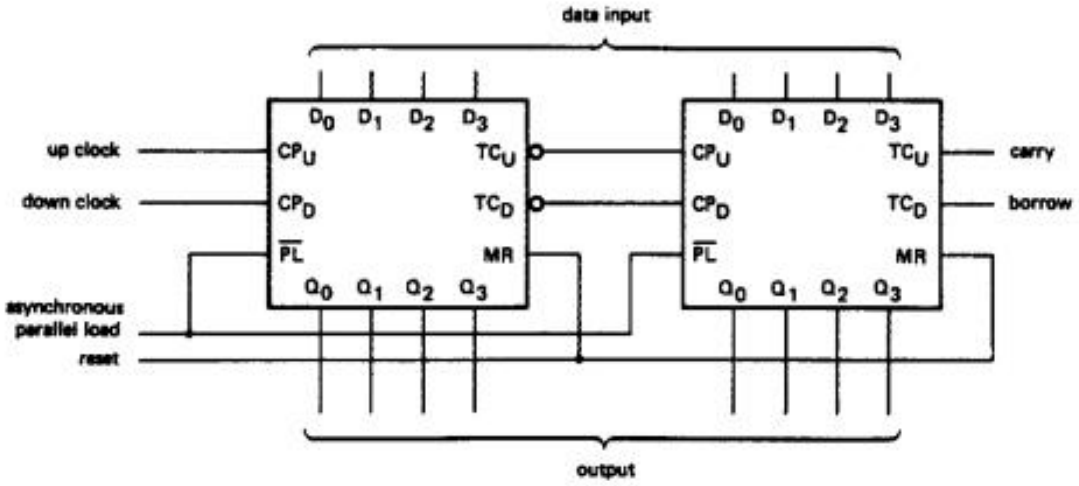
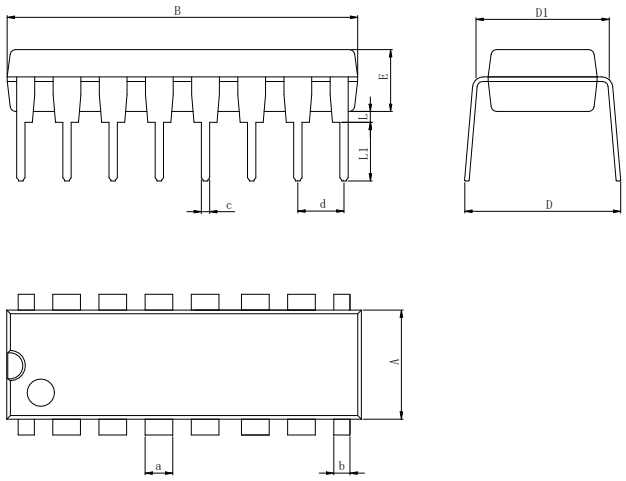


Fig.14 Cascaded up/down counter with parallel load.

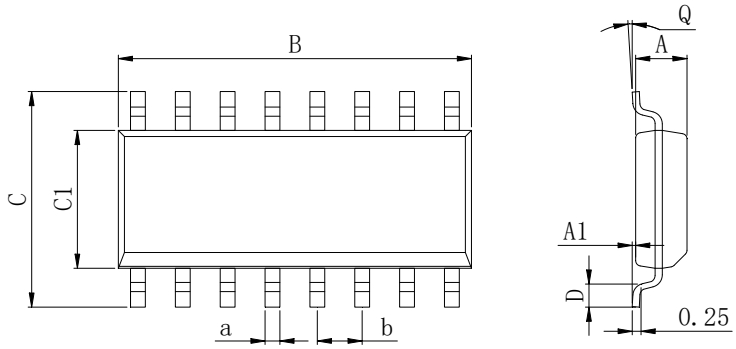
PHYSICAL DIMENSIONS

DIP-16



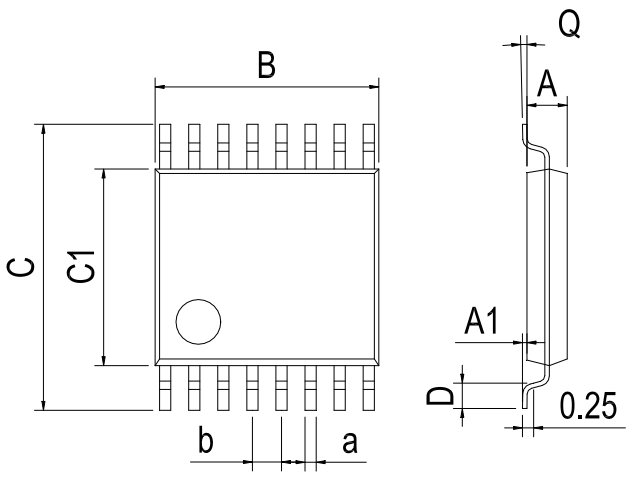
Dimensions In Millimeters(DIP-16)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	18.94	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	19.56	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

SOP-16



Dimensions In Millimeters(SOP-16)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	9.80	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	10.0	6.20	4.00	0.80	8°	0.45	

TSSOP-16



Dimensions In Millimeters(TSSOP-16)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	

REVISION HISTORY

DATE	REVISION	PAGE
2018-9-8	New	1-17
2023-9-15	Modify the package dimension diagram TSSOP-16、Update encapsulation type、Update Soldering temperature、Updated DIP-16 dimension	1、3、14、15

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